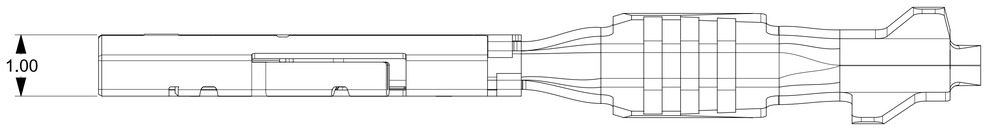
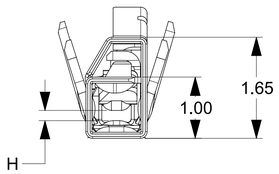
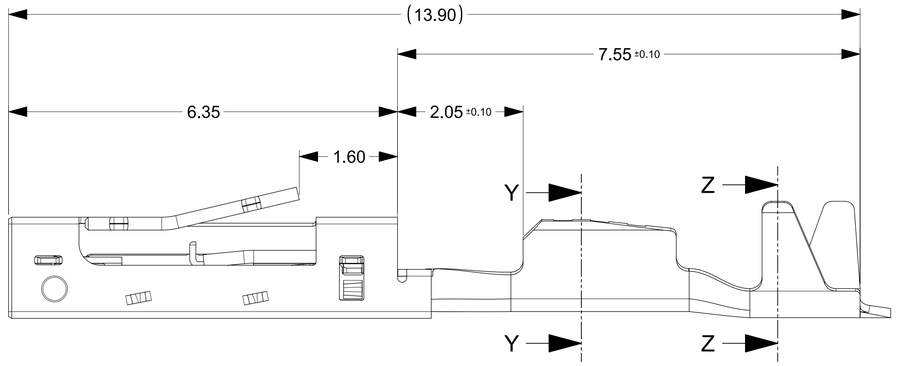
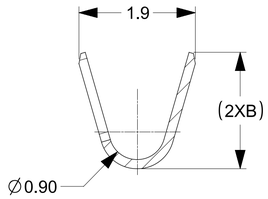


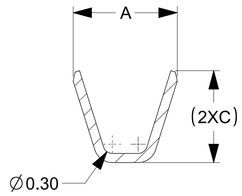
TABLE 1												
Part Number	DESCRIPTION	STATUS	Marking Type	Top Layer Plating Type	Grip Code	Wire Insulation OD - mm	Wire Size - mm²	Pay Off Direction	Dimensions - mm			
									Dim A ± 0.10	Dim B ± 0.10	Dim C ± 0.10	Dim H ± 0.05
2000960101	STANDARD	ACTIVE	LTG	Sn	L	1.2-1.3	0.35	D	1.7	1.9	1.5	0.17
2000960201			STG	Sn	S	0.95-1.05	0.13	D	1.6	1.8	1.25	0.17
2000960161			LTG	Sn	L	1.2-1.3	0.35	B	1.7	1.9	1.5	0.17
2000960261			STG	Sn	S	0.95-1.05	0.13	B	1.6	1.8	1.25	0.17
2000960102	HIGH PERFORMANCE	IN DEVELOPMENT	LMH	Sn	L	1.2-1.3	0.35	D	1.7	1.9	1.5	0.24
2000960202			SMH	Sn	S	0.95-1.05	0.13	D	1.6	1.8	1.25	0.24
2000960162			LMH	Sn	L	1.2-1.3	0.35	B	1.7	1.9	1.5	0.24
2000960262			SMH	Sn	S	0.95-1.05	0.13	B	1.6	1.8	1.25	0.24



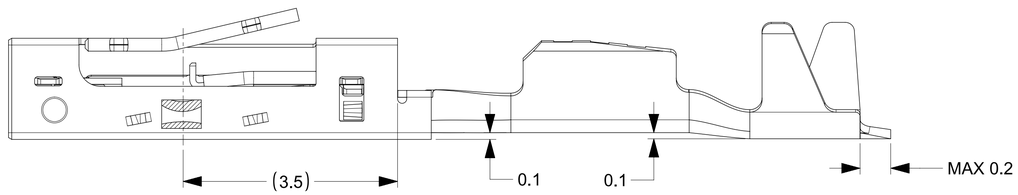




SECTION Z-Z



SECTION Y-Y



NOTES: (UNLESS OTHERWISE SPECIFIED)

1. MATERIAL: COPPER ALLOY

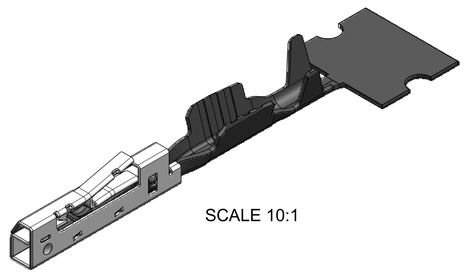
2. PLATING: SEE TABLE 1

3. PACKAGING SPEC: 313025040

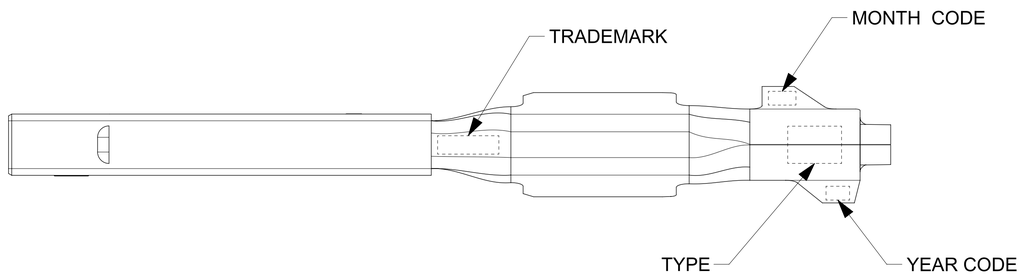
4. CRIMPING SPEC: 2000960001

5. PRODUCT SPEC: 2000960000

6. PROBING THE CONTACT INTERFACE OF THE TERMINAL OR AT ANY POINT ON THE TERMINAL BEAM IS NOT PERMITTED



SCALE 10:1



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QUALITY SYMBOLS: EA = 0; EC = 0; EP = 0; ▼ = 0; C = 0; ☒ = 0; ■ = 0; ▽ = 0

EC NO: 632318
DRWN: RSETHURAMAN 2019/12/19
CHK'D: BMOSER 2020/02/19
APPR: BMOSER 2020/02/19

GENERAL TOLERANCES (UNLESS SPECIFIED)

ANGULAR TOL	±	1.0 °
4 PLACES	±	0.01
3 PLACES	±	0.015
2 PLACES	±	0.05
1 PLACE	±	0.1
0 PLACES	±	0.2

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

REV: C

DIMENSION UNITS: mm
SCALE: 20:1
DRWN BY: NBHAGYANATHA DATE: 2014/10/10
CHK'D BY: DATE:
APPR BY: YLEPOTTIER DATE: 2016/03/28
DRAWING SIZE: A1
THIRD ANGLE PROJECTION

molex®

MOLEX TAK50_WR_TERM_RCPT UNSEALED

PRODUCT CUSTOMER DRAWING

SERIES	MATERIAL NUMBER	CUSTOMER
200096		

DOCUMENT NUMBER	DOC TYPE	DOC PART	SHEET NUMBER
2000960001	PSD	000	1 OF 1

RELEASE STATUS	P1	RELEASE DATE	2020/02/19 18:06:22

FORMAT: 4sizeBundle47
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DATE: 2016/3/14